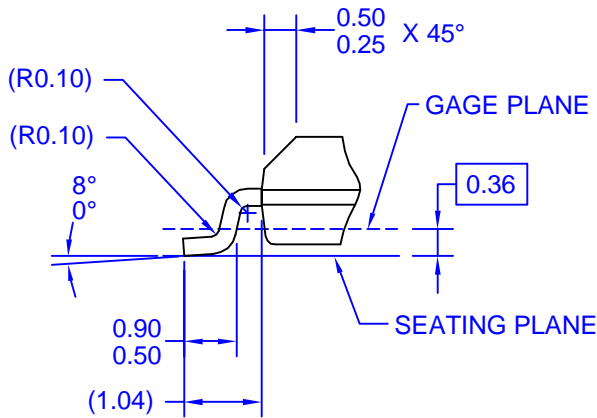
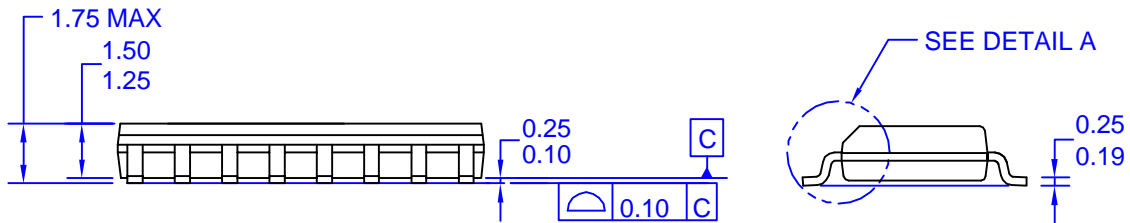
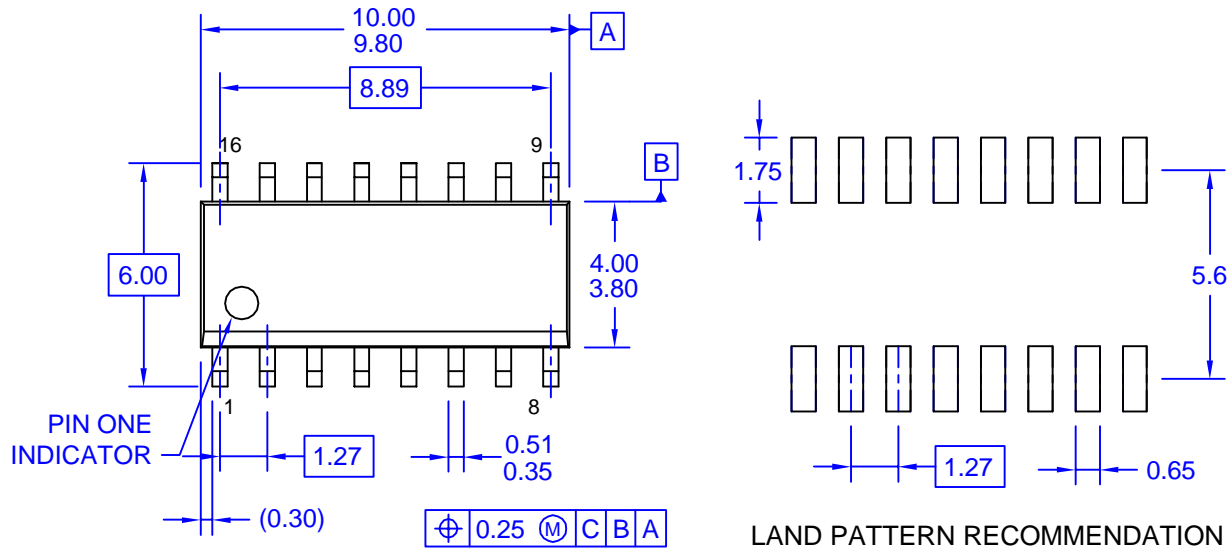


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APPD
G	REVISE AND REDRAWN	04038	09/10/99	JMR/N
H	INCORPORATE NSC & FSC DWGS: REVISE DIM & NOTES.	05925	10/04/88	DEG
J	CHANGE LEAD TIP FROM TAPER TO SQUARE	11069	AUG 29/95	FEITAN
K	REDRAW AS PER NEW DWG TEMPLATE; CHG DUAL DIM INCH(MM) TO SINGLE DIM MM; CHG LEADSPREAD FR LIMITS TO BASIC; CHG PKG FOOT LENGTH DIM FR LIMITS TO SYM TOL; ADD TOL ON PKG THICK DIM; CHG PROFILE TOL FROM LIMITS TO DEVIATION; ADD GAGE PLANE DIM; ADD LAND PATTERN DIM.	CB/060/99	OCT.15/99	MRG
11	UPDATED TO CONFORM TO FSC-MKT-0001		6 JULY 07	L.HUEBENER
12	ADOPTED JEDEC LEADSPREAD VALUE	ECN-MKT-M16AR12	31 JULY 07	L.HUEBENER



DETAIL A
SCALE: 2:1

NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AC, ISSUE C.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS
- D) CONFORMS TO ASME Y14.5M-1994
- E) LANDPATTERN STANDARD: SOIC127P600X175-16AM
- F) DRAWING FILE NAME: M16AREV12.

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™			
DRAWN: L.HUEBENER	31 JULY 07	16LD, SOIC, JEDEC MS-012 .150" NARROW BODY			
CHECKED: H.ALLEN	2 AUG 2007				
APPROVED:					
		SCALE 1:1	SIZE NA	DRAWING NUMBER MKT-M16A	REV 12
		FORMERLY: N/A	SHEET: 1 OF 1		